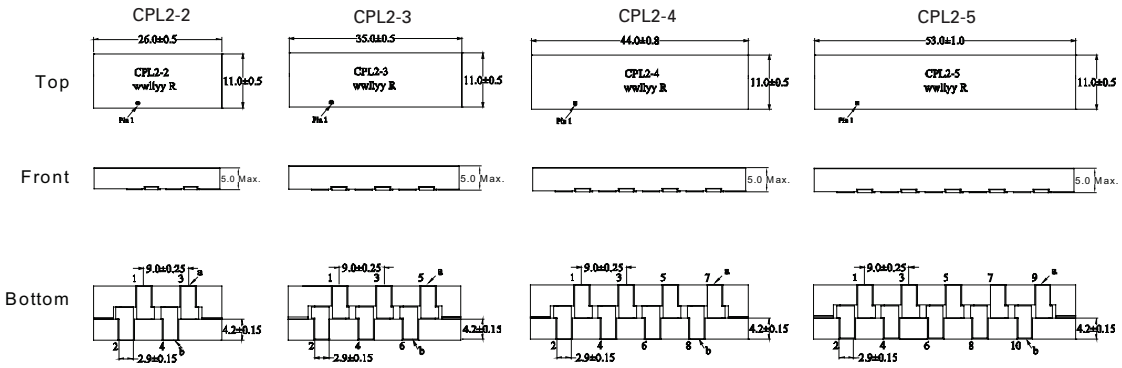
Product Specifications

	Function Specifications					Test Specifications				
Part Number[4,5]	**Inductor phases**	**DCR (Ω) ±10% @25°C**	**Rated Inductance per Phase[3] (nH)**	**I Rated per Phase[3] (ADC)**	**Imax Peak per Phase[3] (ADC)**	**Pin numbers**	**OCL[1,2] (nH)**	**Pin numbers**	**OCL[1,2] (nH)**	**Magnetizing Inductance[2] (nH) @ 10ADC (25°C)**
CPL2-2-50TR-R	2	0.00028	50 ± 20%	50	80	(1-2)	380±20%	(3-4)	380±20%	300
CPL2-3-50TR-R	3	0.00028	50 ± 20%	50	80	(3-4)	400±20%	(1-2), (5-6)	380±20%	300
CPL2-4-50TR-R	4	0.00028	50 ± 20%	50	80	(3-4), (5-6)	400±20%	(1-2), (7-8)	380±20%	300
CPL2-5-50TR-R	5	0.00028	50 ± 20%	50	80	(3-4), (5-6), (7-8)	400±20%	(1-2), (9-10)	380±20%	300

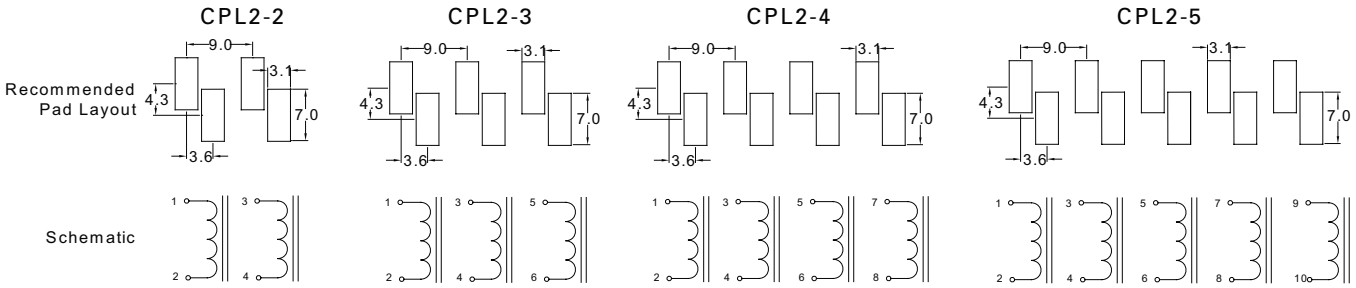
1. OCL (Open Circuit Inductance)
2. Test parameters: 1MHz, 0.1Vrms, 0.0Adc. @25°C
3. The rated current and rated inductance per phase is determined by Volterra's testing and circuit design. Additional information can be provided by contacting Volterra.
4. Part Number Definition: CPL2-x-50TR-R
   - CPL2= Product code and size
   - -x= number of phases
   - -50 = rated inductance value per phase in nH
   - TR= Tape and reel
   - -R suffix= RoHS compliant
5. This device is licensed for use only when incorporated within a voltage regulator employing power regulating devices manufactured by Volterra Semiconductor, LLC or Maxim Integrated Devices, Inc. No license is granted expressly or by implication to use this device with power regulating devices manufactured by any company other than Volterra or Maxim.

Dimensions (mm)



Part marking: Pin 1 dot, CPL2= (product code and size),-2,-3,-4,-5, = (number of phases)
wwllyy = date code, R = revision level
Tolerances are ±0.25 millimeters unless stated otherwise
All soldering surfaces to be coplanar within 0.13 millimeter
Do not route traces or vias underneath the inductor

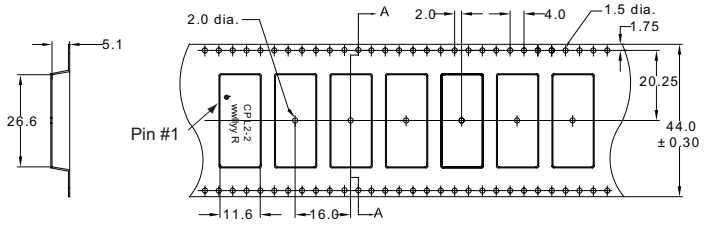
Pad layouts & schematics (mm)



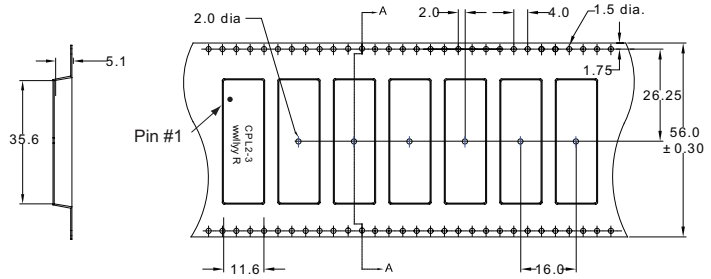
Packaging Information (mm)

Supplied in tape-and-reel packaging on a 13″ diameter reel.

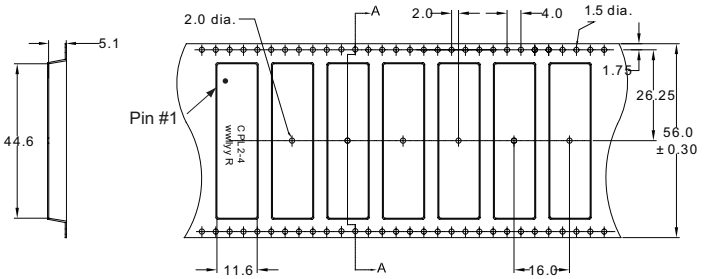
CPL2-2
750 parts per reel



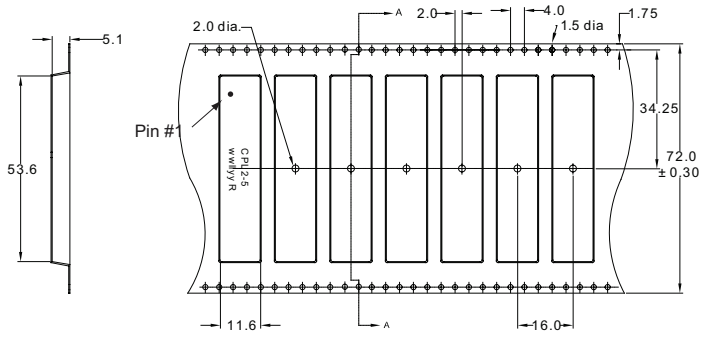
CPL2-3
600 parts per reel



CPL2-4
500 parts per reel



CPL2-5
400 parts per reel



Section A-A

User Direction of feed

Solder reflow profile

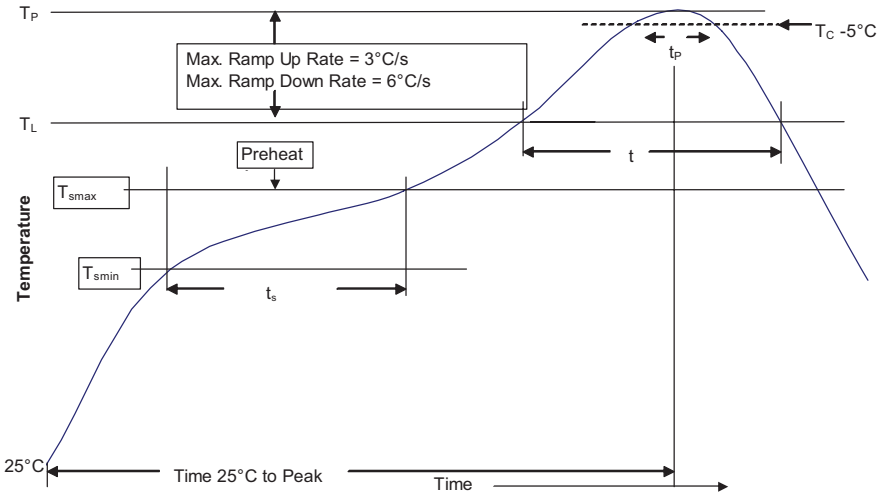


Table 1 - Standard SnPb Solder (T_C)

Package Thickness	Volume mm3 <350	Volume mm3 ≥350
<2.5mm)	235°C	220°C
≥2.5mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder (T_C)

Package Thickness	Volume mm^3 <350	Volume mm^3 350 - 2000	Volume mm^3 >2000
<1.6mm	260°C	260°C	260°C
1.6 – 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

Reference JDEC J-STD-020D

Profile Feature		Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak	• Temperature min. (T_{smin})	100°C	150°C
	• Temperature max. (T_{smax})	150°C	200°C
	• Time (T_{smin} to T_{smax}) (t_s)	60-120 Seconds	60-120 Seconds
Average ramp up rate T_{smax} to T_p		3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature (T_L) Time at liquidous (t_L)		183°C 60-150 Seconds	217°C 60-150 Seconds
Peak package body temperature (T_P)*		Table 1	Table 2
Time (t_p)** within 5 °C of the specified classification temperature (T_C)		20 Seconds**	30 Seconds**
Average ramp-down rate (T_p to T_{smax})		6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature		6 Minutes Max.	8 Minutes Max.

* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.
** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

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